

- L2: (61) "647274" "560054" "20040856277".pn.
- L2: (12) Backward citation search 1
- L4: (45) Forward citation search 1
- L5: (182561) | heatsink | (heat thermal\$2) near (sink\$4 spread\$3 dissipat
- L6: (156781) undercut under adj cut
- L7: (1105) L5 with L6
- L8: (94040) t near shap\$4
- L9: (481492) interpos\$4
- L10: (1110) 5 near 4 8
- L11: (85808) notched
- L12: (458271) (undercut under adj) cut T near shap\$4 notch1
- L13: (816788) 5 8
- L14: (12059) 19 near 9 12
- L15: (519424) (undercut under adj) cut T near shap\$4 notch\$41
- L16: (23061) 19 near 9 15
- L17: (79554) wir\$4 near bond\$4
- L18: (17) 16 same 17
- L19: (136) 16 and 17
- L20: (4) "6369455".pn. "8851028".pn.
- L21: (12) Backward citation search 2
- L22: (8) Forward citation search 2
- L23: (8) Forward citation search 3
- L24: (8) Forward citation search 4
- L25: (9) Backward citation search 9
- L26: (57) Forward citation search 5

(16 out of 20) 12

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	U	S	Inventor	Document	Issn	P	Title	Current	Current E	Retrieval	S	C	P	Image	Doc	P
1			Zhao, Sam	Z US	6887741	2005	5	Method for making an enhanced die-u	438/12							US 688774
2			Zhao, Sam	Z US	688204	2005	2	Thermally and electrically enhanced b	257/70	257/712;						US 68820
3			Cheah, Eng	US	6882041	2005	0	Thermally enhanced metal capped B	257/70	257/687;						US 68820
4			Khan, Reza-	US	687903	2005	2	Ball grid array package substrates and	257/73	257/678;						US 687903
5			Zhao, Sam	Z US	687655	2005	5	Enhanced die-up ball grid array packa	381/78	381/784						US 687655
6			Zhao, Sam	Z US	6861750	2005	3	Ball grid array package with multiple l	257/73	257/688;						US 686175
7			Khan, Reza-	US	685307	2005	2	Die-down hall grid array package with	257/707	257/717;						US 685307
8			Chan, Vince	US	684894	2005	11	Integrated circuit package for the tran	257/70	257/675;						US 684894
9			Khan, Reza-	US	682510	2004	12	Ball grid array package fabrication wit	438/61	257/734;						US 682510
10			Yonemochi,	US	6818478	2004	11	Insert-moldable heat spreader, semic	438/12	257/E23.0						US 681847

人 数 3 名

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